



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
 [List multiple models if applicable.]

HP Compaq 6080 Pro Microtower PC

Name / Model #2

Name / Model #3

Name / Model #4

Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	2
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		3
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		

Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screwdriver	T-15
Micro shear	170II
Screwdriver	PH1
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. SYSTEM BOARD

1.1 Remove the access panel:

- a) Remove the two screws that secure the access panel to the computer chassis. (see Figure 1 below)
- b) Lift the panel off the unit. (see Figure 2 below)

1.2 Disconnect the data cables from the board.(see Figure 3-7 below)

- a) Disconnect the speaker cable and system fan cables from the board.
- b) Disconnect the ODD cable and HDD cable from the board.
- c) Disconnect the power switch cable and Card reader cable from the board.

1.3 Remove the front chassis fan.(see Figure 8-10 below)

- a) Remove the cables from the top of the fan cover.
- b) Pull the handle on the fan cover next the HDD cage.
- c) Rotate the fan cover and lift it off the unit.

1.4 Remove the Memery.(see Figure 11 below)

1.5 Remove the processor from the system board: (see Figure 12-14 below)

- a) Loosen the clip that secures the heat sink to the system board.
- b) Lift the heat sink from atop the processor and set it on its side to keep from contaminating the work area with thermal grease.

c) Rotate the handle and lift the processor from the socket.

d) Restoration the socket handle.

1.6 Remove the system board: (see Figure 15&16 below)

a) Remove the screws that secure the system board to the chassis .

b) Lift the system board towards then remove it.

2. BATTERY

2.1 Release the battery from its holder, squeeze the metal clamp that extends above one edge of the battery. Then the battery pops up, lift it out.(see Figure 17 below).

3. SYSTEM DRIVERS

3.1 Remove the HDD.(see Figure 18&19 below)

a) Remove the cables connect to the HDD.

b) Pull the handle and lift the HDD off the unit.

3.2 Remove the ODD.(see Figure 20-26 below)

a) Remove the cables connect to the ODD.

b) Pull outward on all three tabs on the left side of the front bezel.

b) Rotate the bezel off the chassis.

d) Lift the handle and pull the ODD out of the ODD cage.

3.3 Remove the shielding.(see Figure 27&28 below)

a) Turn handle on the top of the shielding.

b) Remove the shielding.

3.4 Remove the rear chassis fan.(see Figure 29&30 below)

a) Remove the screws.

b) Take off the fan from the unit.

3.5 Remove the front I/O.(see Figure 31&32 below)

a) Remove the screw.

b) Rotate the Front I/O and pull it out of the chassis.

3.6 Remove the speaker.(see Figure 33&34 below)

a) Remove the screw.

b) Left the speaker and pull it out of the chassis.

3.7 Remove the power on/off switch.(see Figure 35&36 below)

a) Extrusion the bottom of the switch.

b) Pull the switch out of the chassis.

4. POWER SUPPLY

4.1 Take off the power supply: (see Figure 37&38 below)

a) Remove the four screws that secure the power supply to the chassis.(see Figure 8 below)

c) Press the baffle and slide the power supply toward the front of the computer, then lift it out of the chassis.(see Figure 9 below)

4.2 Remove the cover from the power supply: (see Figures 39-41 below)

a) Using a phillips screwdriver, remove the four screws that secure the cover to the power supply chassis.

b) Cut the plastic cable clamp that secures the cables to the cover.

c) Lift the cover off the power supply.

4.3 Remove the power supply PCA: (see Figure 42-44 below)

a) Remove the four screws that secure the power supply PCA to the chassis.(see Figure 14 below)

b) Using Soldering Iron, heat the solder of the cables which connect to the PCA, then remove the cables.(see Figure 15&16 below)

c) Remove the power supply PCA from the power supply chassis.

4.4 Remove the Electrolytic Capacitors:(see Figure 45&46 below)

a) Using Soldering Iron, heat the solder of Electrolytic Capacitors.

b) Remove the Electrolytic Capacitors.

5.

6.

7.

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11.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Figure 1: Remove the two screws



Figure 2: Lift the access panel



Figure 3: Disconnect the cables from the board

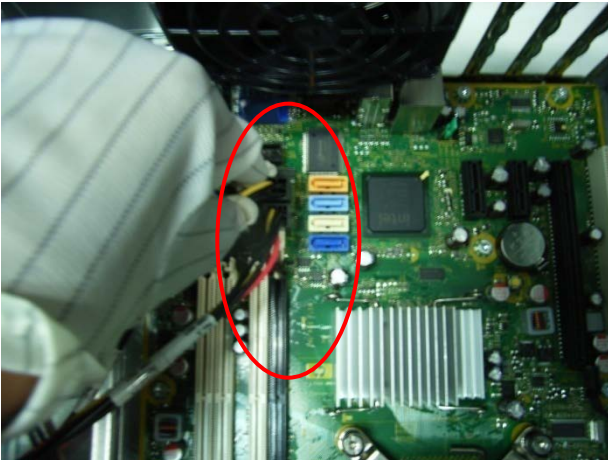


Figure 4: Disconnect the cables from the board

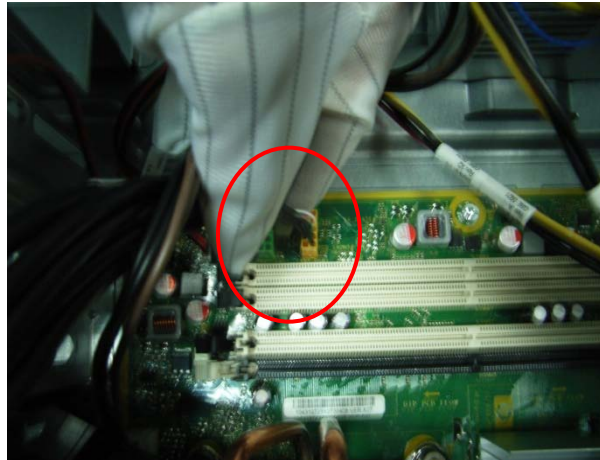


Figure 5: Disconnect the cables from the board

Figure 6: Disconnect the cables from the board

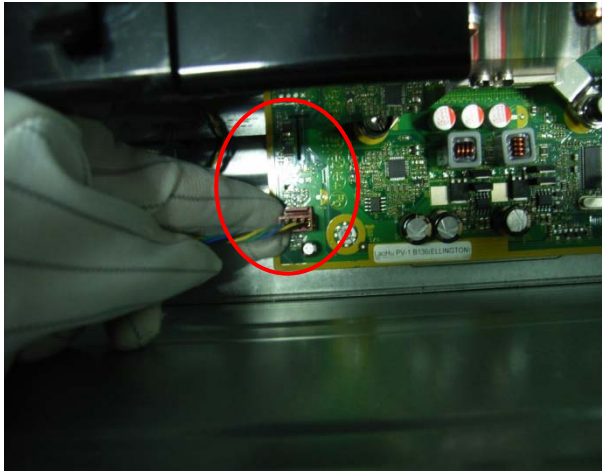


Figure 7: Disconnect the cables from the board

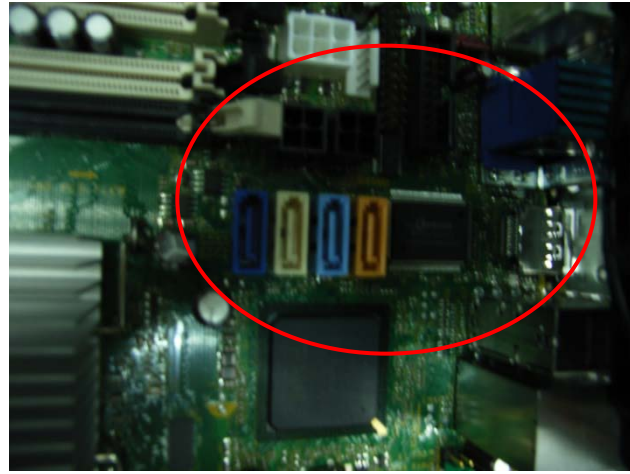


Figure 8: Remove the cables from the top of the fan cover.

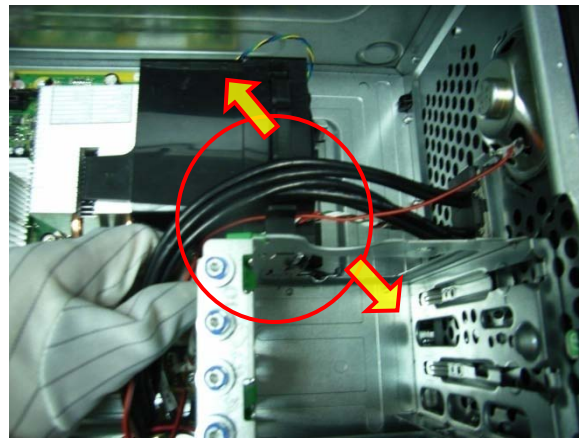


Figure 9: Pull the handle on the fan cover next the HDD cage

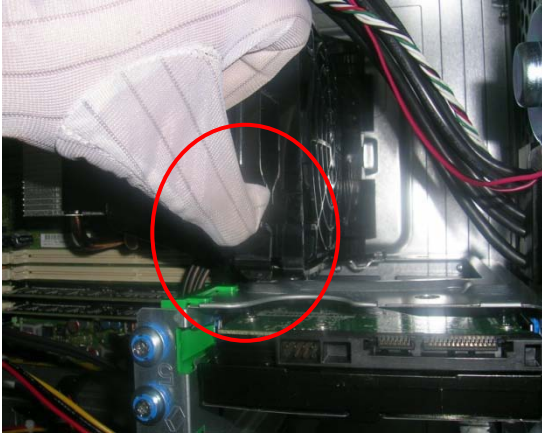


Figure 10: Rotate the fan cover and lift it off the unit.

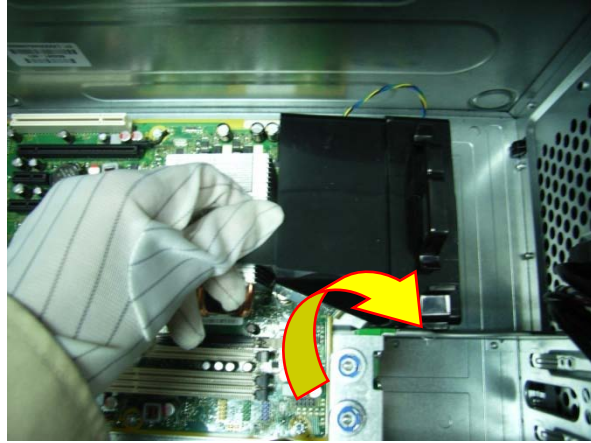


Figure 11: Remove the Memory.

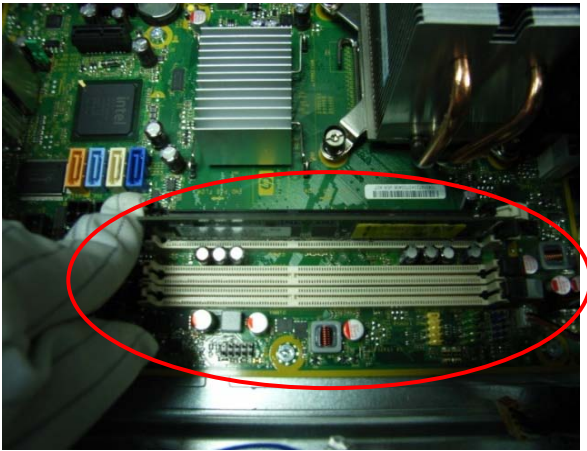


Figure 12: Loosen the clip that secures the heat sink to the system board.

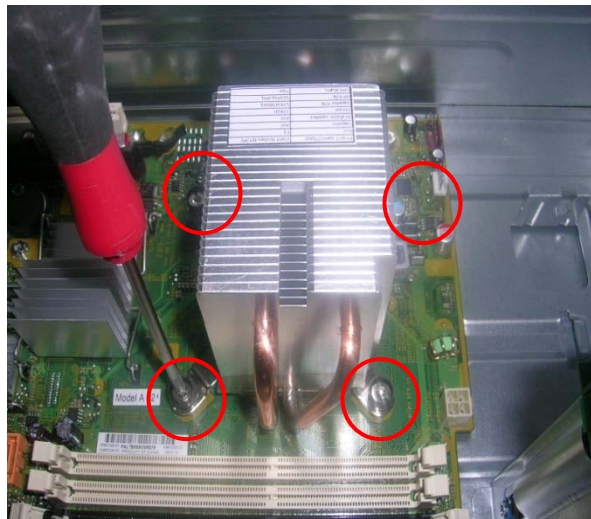


Figure 13: Rotate the handle



Figure 14: Lift the processor from the socket



Figure 15: Remove the screws that secure the system board to the chassis



Figure 16: Lift the system board towards then remove it



Figure 17: Remove the battery



Figure 18 : Remove the cables connect to the HDD

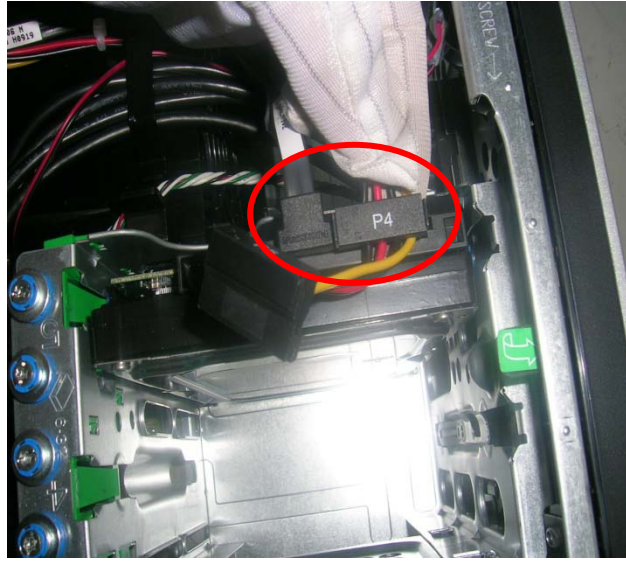


Figure 19 : Pull the handle and lift the HDD off the unit



Figure 20 : Remove the cables connect to the ODD

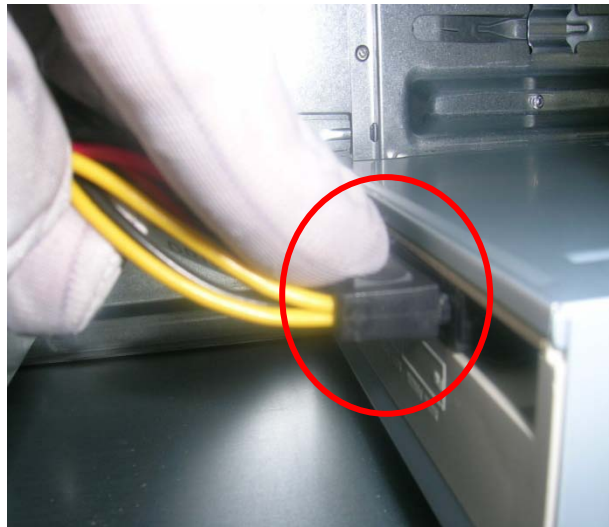


Figure 21: Pull outward on all three tabs on the left side of the front bezel

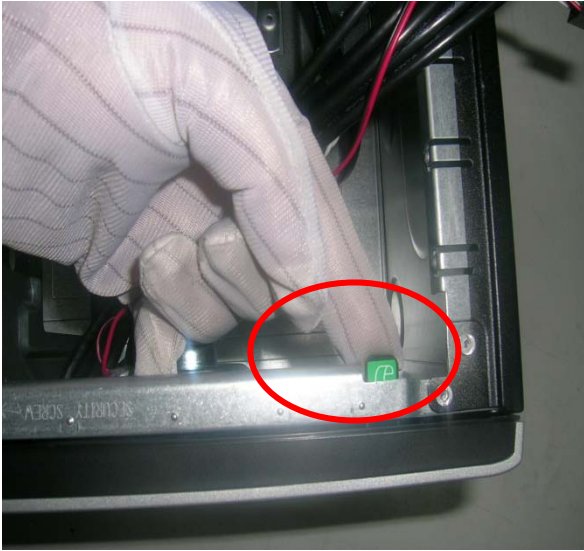


Figure 22: Pull outward on all three tabs on the left side of the front bezel

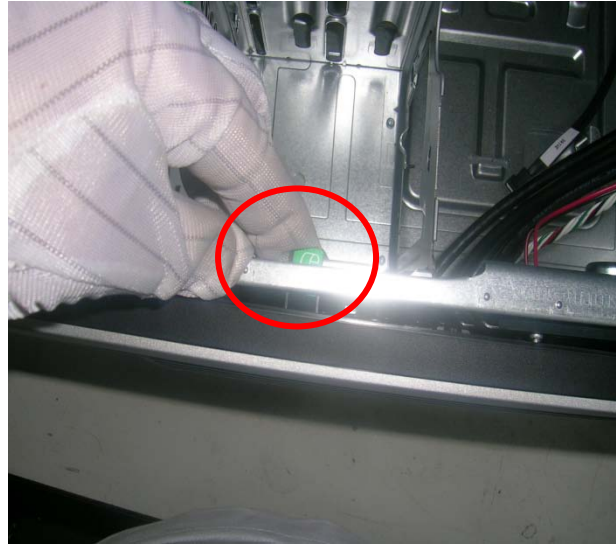


Figure 23: Pull the handle and lift the HDD off the unit

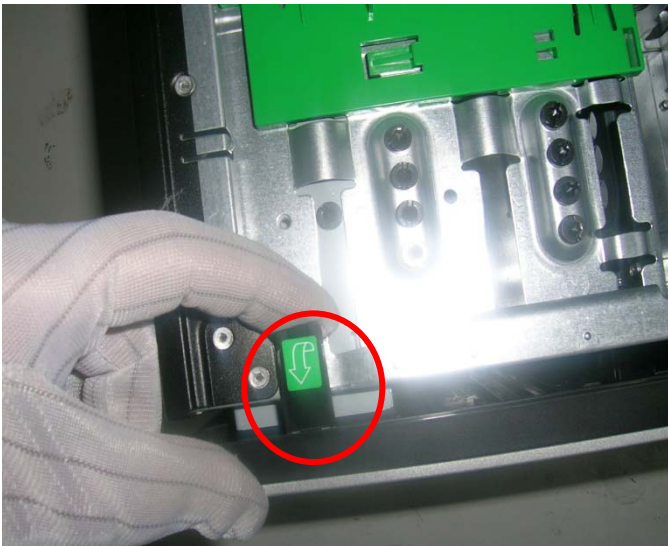


Figure 24: Rotate the bezel off the chassis

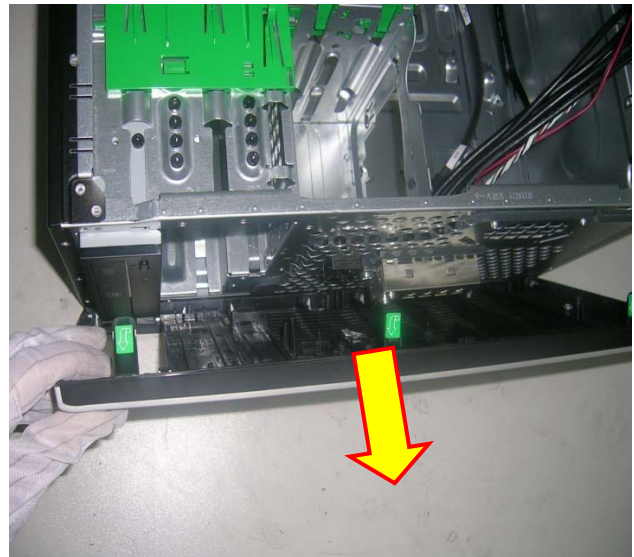


Figure 25: Pull outward on all three tabs on the left side of the front bezel

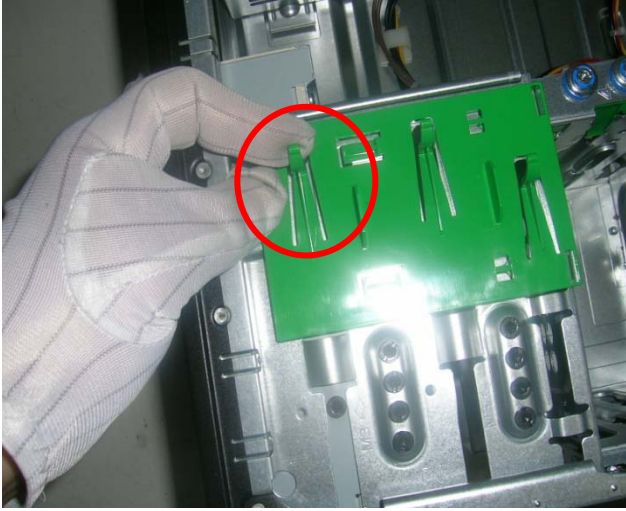


Figure 26: Pull outward on all three tabs on the left side of the front bezel

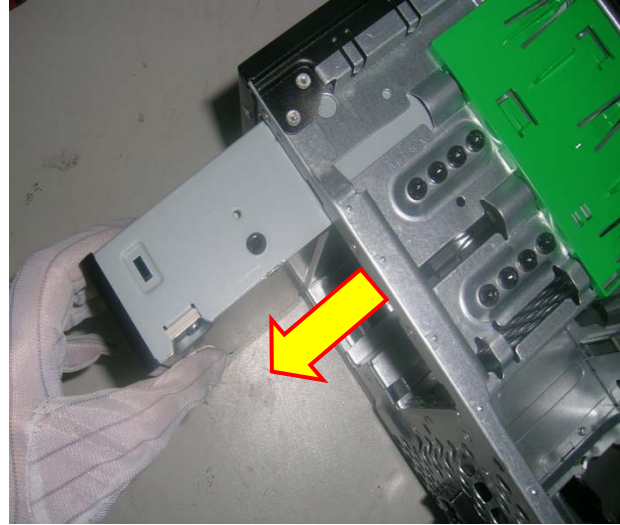


Figure 27: Turn handle on the top of the shielding

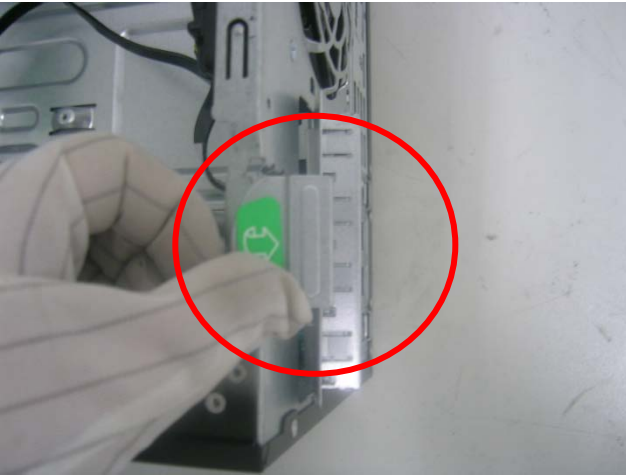


Figure 28: Remove the shielding

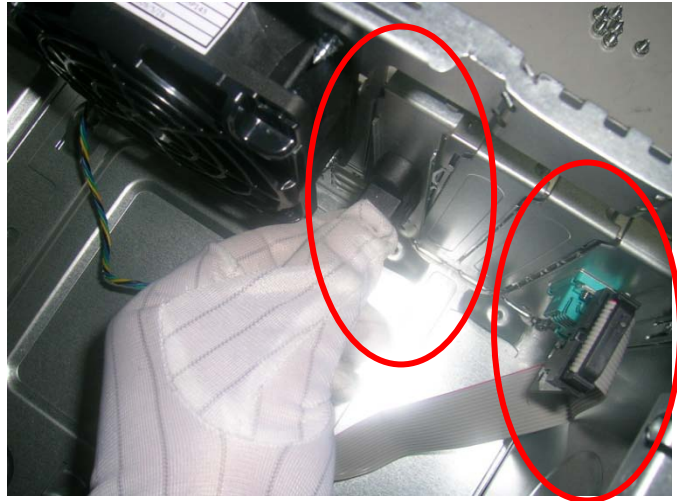


Figure 29: Remove the rear chassis fan screws

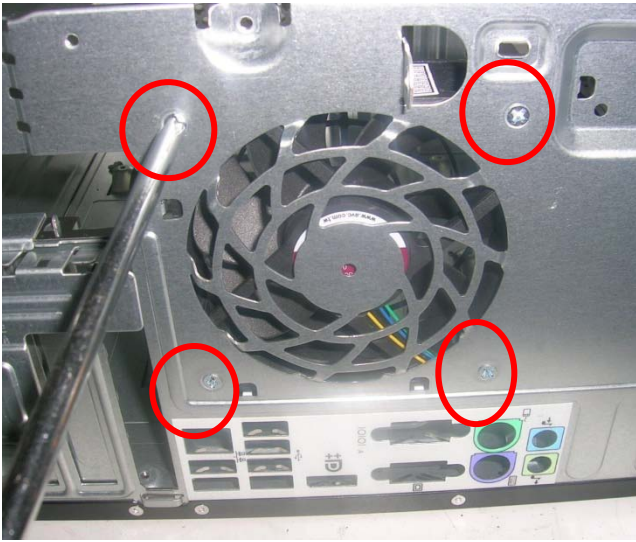


Figure 30: Take off the fan from the unit

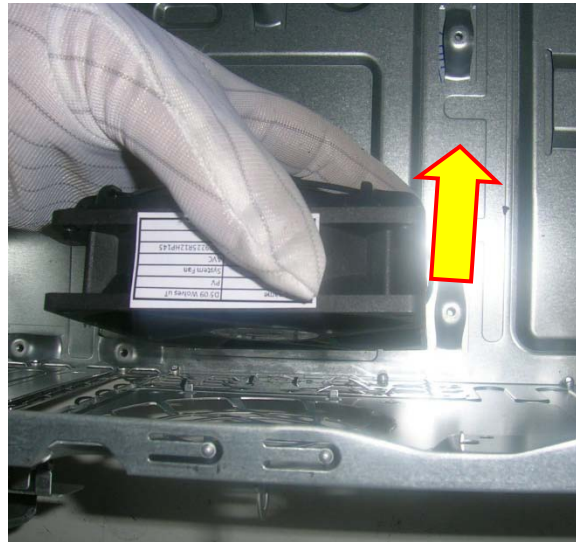


Figure 31: Remove the front I/O screw

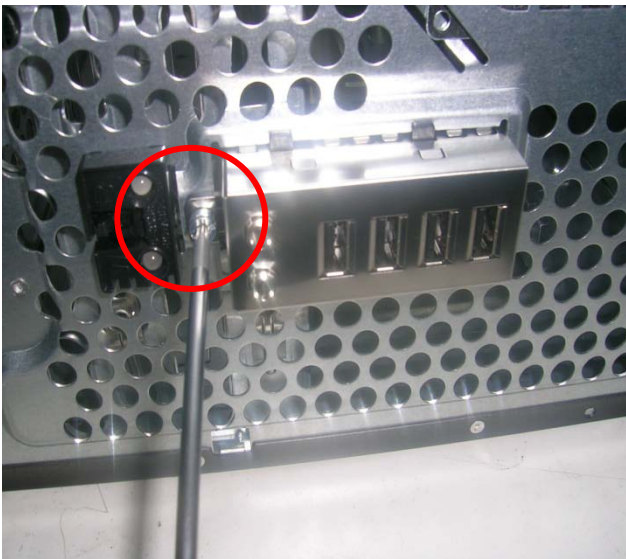


Figure 32: Rotate the Front I/O and pull it out of the chassis



Figure 33: Remove the speaker screws

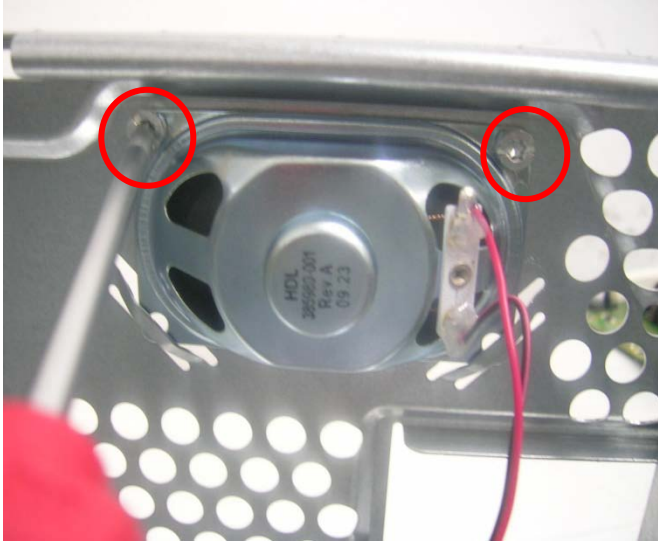


Figure 34: Left the speaker and pull it out of the chassis



Figure 35: Extrusion the bottom of the power on/off switch



Figure 36: Pull the power on/off switch out of the chassis

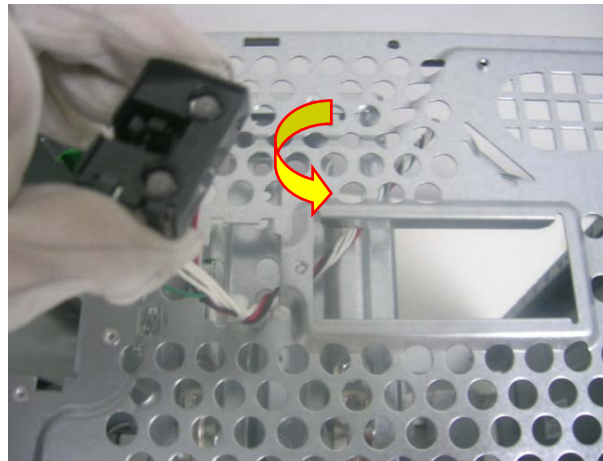


Figure 37: Remove the power supply screws

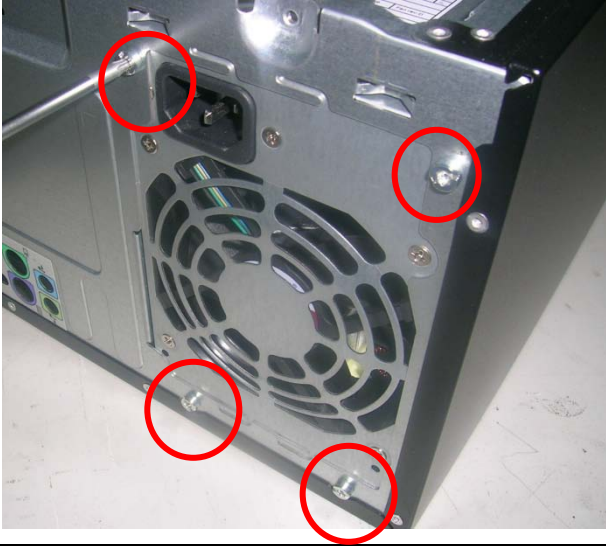


Figure 38: Press the baffle and slide the power supply toward the front of the computer

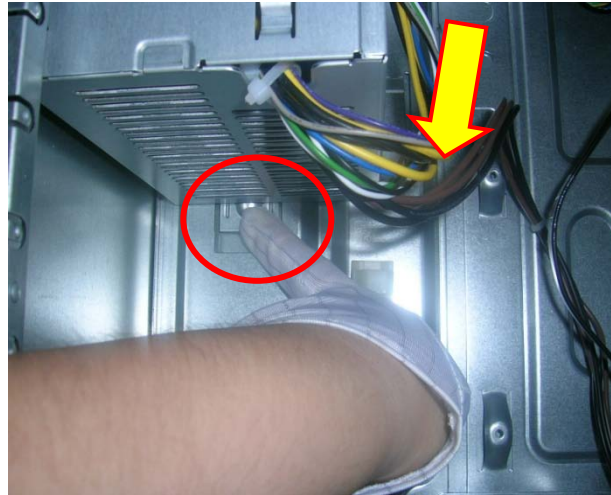


Figure 39: Remove the screws that secure the cover to the power supply chassis

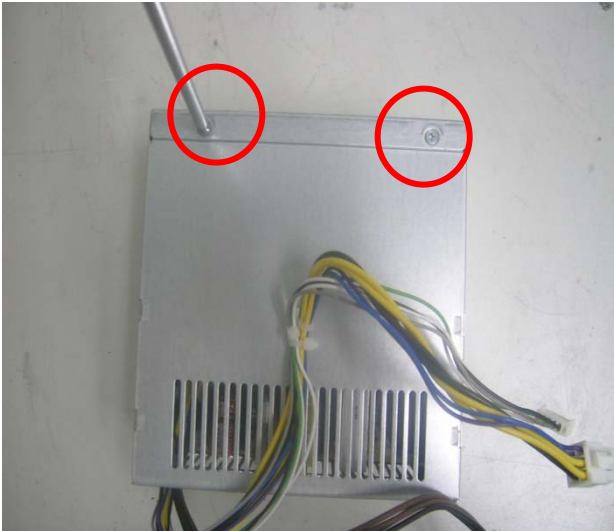


Figure 40: Cut the plastic cable clamp that secures the cables to the cover

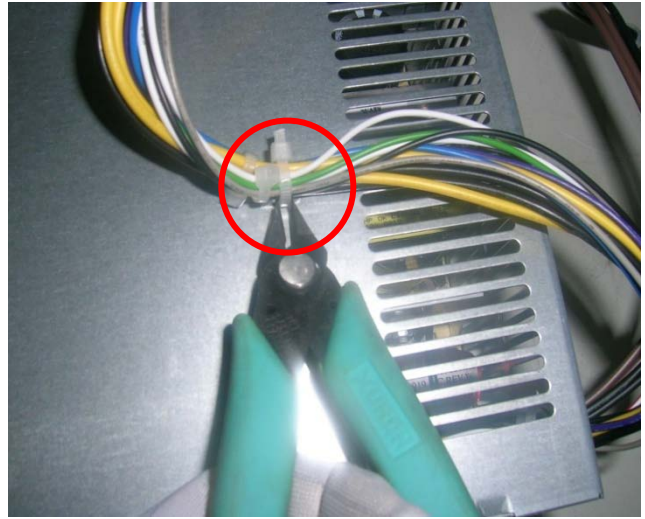


Figure 41: Lift the cover off the power supply



Figure 42: Remove the four screws that secure the power supply PCA to the chassis

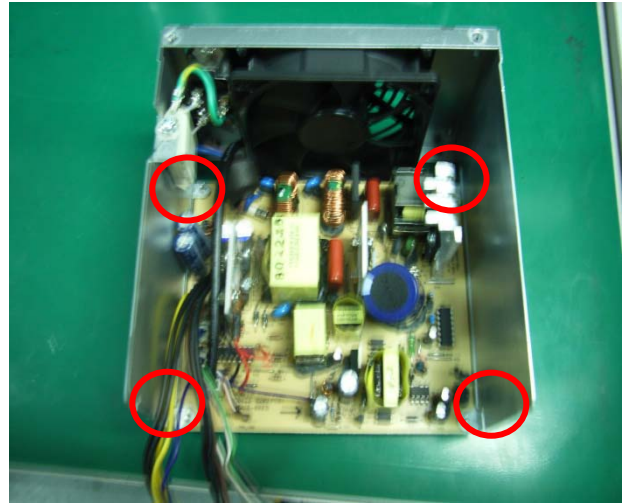


Figure 43: Using Soldering Iron, heat the solder of the cables which connect to the PCA, then remove the cables

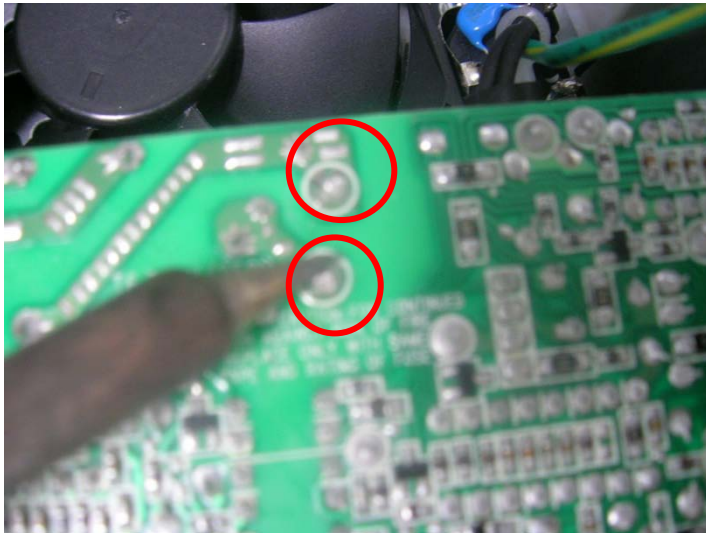


Figure 44: Remove the power supply PCA from the power supply chassis

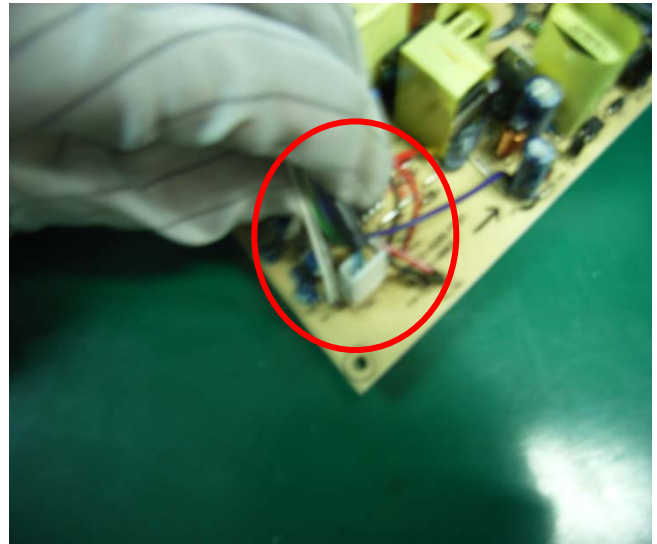


Figure 45: Using Soldering Iron, heat the solder of Electrolytic Capacitors

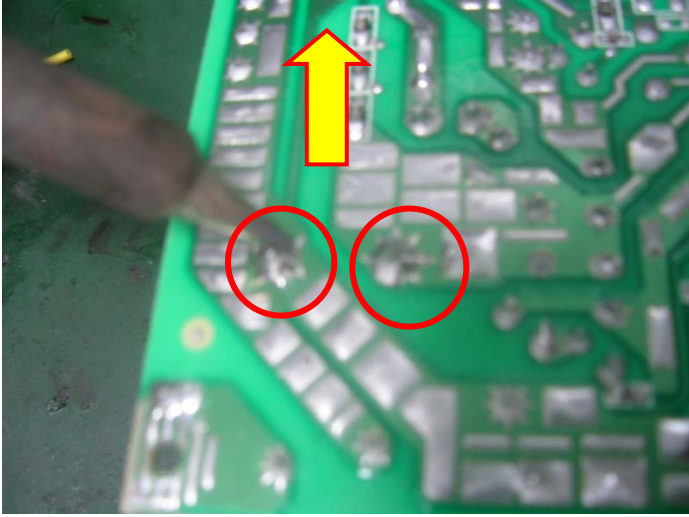


Figure 46: Remove the Electrolytic Capacitors

